

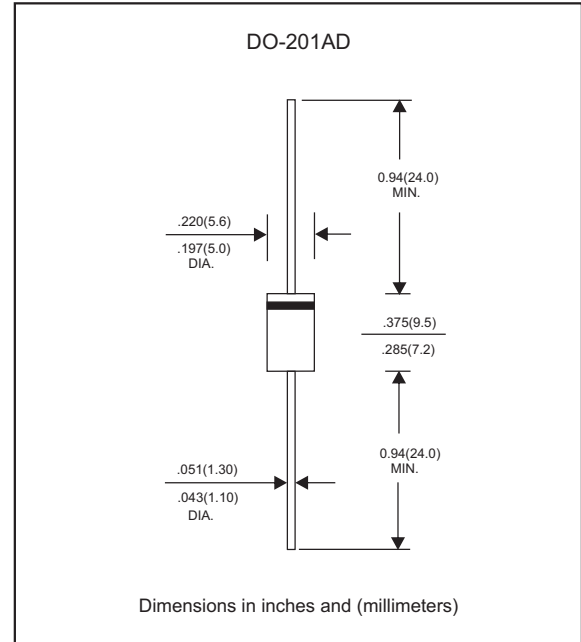
Features

- Axial lead type devices for through hole design
- High current capability.
- Superfast recovery time for switching mode application,
- High surge capability.
- Glass passivated chip junction structure.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. SF31G-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-201AD
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any

Package outline



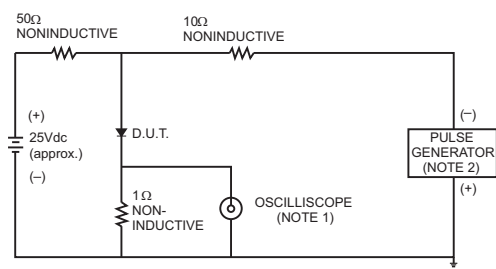
Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

	SYMBOLS	SF31G	SF32G	SF33G	SF34G	SF35G	SF36G	SF37G	SF38G	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	500	600	V
Maximum average forward rectified current 0.375" (9.5mm) lead length at $T_A=55^\circ\text{C}$	I_{AV}	3.0								A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	125								A
Maximum instantaneous forward voltage at 3.0A	V_F	0.95			1.25		1.7			V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	10.0				100.0				μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35								ns
Typical junction capacitance (NOTE 2)	C_J	50.0								pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	20.0								$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150								$^\circ\text{C}$

- Note:** 1.Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3.Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, P.C.B. mounted

Rating and characteristic curves

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

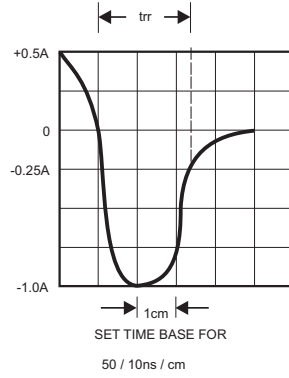


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

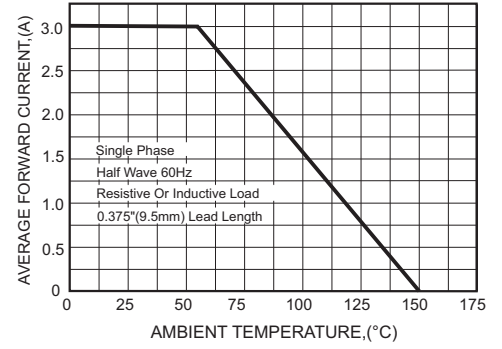


FIG.3-TYPICAL FORWARD CHARACTERISTICS

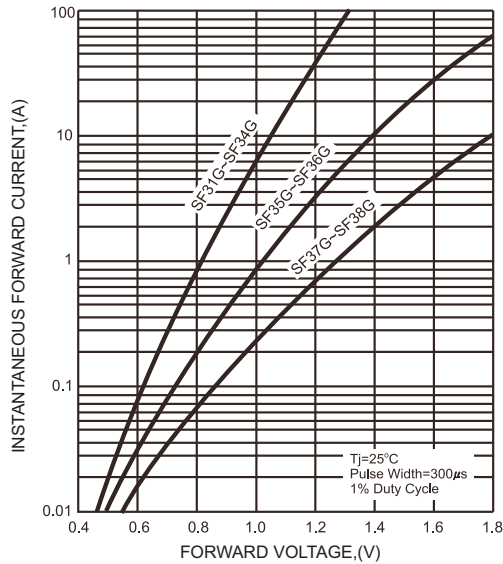


FIG.4-TYPICAL REVERSE CHARACTERISTICS

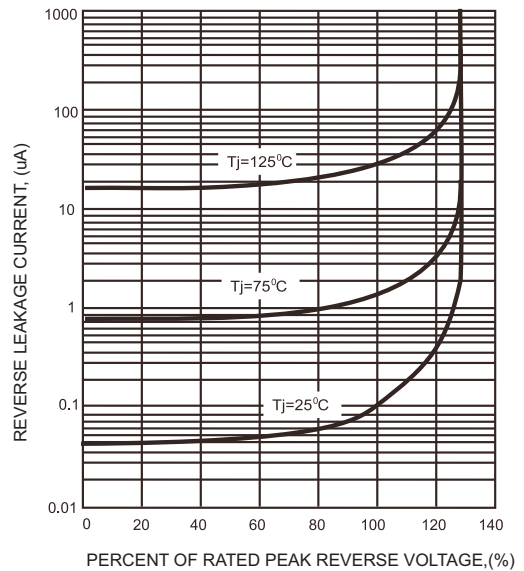


FIG.5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

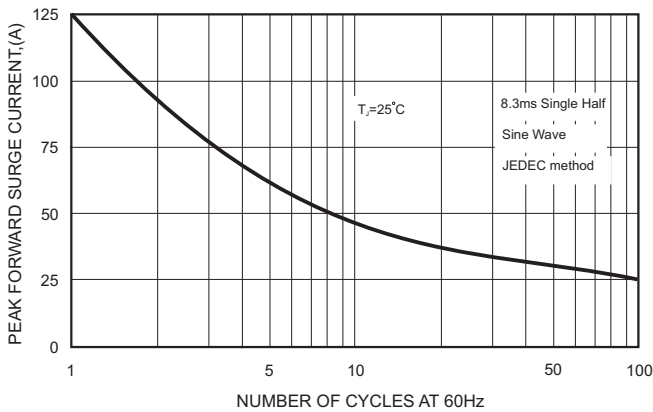
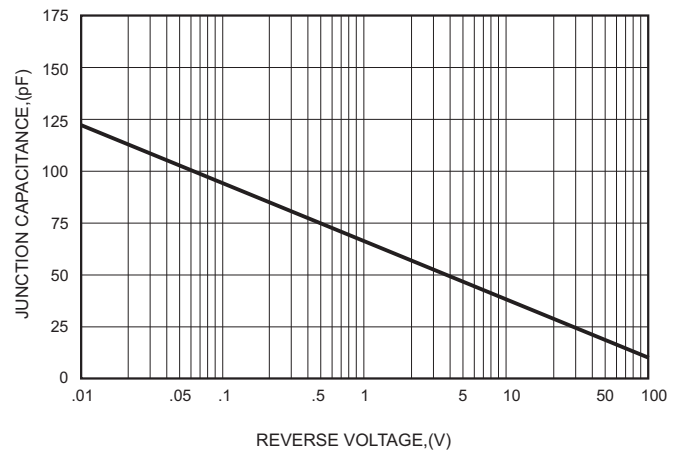


FIG.6-TYPICAL JUNCTION CAPACITANCE



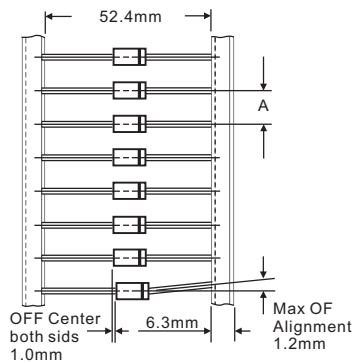
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example	
SF31G	SF31G	For Halogen Device 	For Halogen-free Device
SF32G	SF32G		
SF33G	SF33G		
SF34G	SF34G		
SF35G	SF35G		
SF36G	SF36G		
SF37G	SF37G		
SF38G	SF38G		

Taping specifications for AXIAL devices



AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-201AD	1,250	258 * 75 * 143	405 * 270 * 320	12,500	14.0

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering

